

ABSTRACT

A metal fine particle is adhere to a predetermined location on a substrate. A resist film containing a metallic compound
5 dispersed therein is formed on a substrate (101). A patterning of the resist film is conducted by a lithography. The substrate (101) having the patterned resist formed thereon is heated within an oxygen atmosphere to adhere a metal fine particle (106) to the surface of the substrate (101), while removing the resin in the
10 patterned resist.